



Global Silicon Wafer Japan TC Chapter Meeting Summary and Minutes

Japan Standards-Summer Meetings 2023

Friday, August 25, 2023, 10:00 –12:00[JST]

SEMI Japan Office/Official Virtual TC Chapter Meeting (Hybrid)

TC Chapter Announcements

Next TC Chapter Meeting

Thursday, December 14, 2023, 10:00-12:00 [JST]

Tokyo Big Sight /Official Virtual TC Chapter Meeting (Hybrid) in conjunction with SEMICON Japan 2023

Table 1 Meeting Attendees

Italics indicate virtual participants

Co-Chairs: Name (Company) Tetsuya Nakai (SUMCO), Ryuji Takeda (Global Wafers Japan)

SEMI Staff: Mami Nakajo

<i>Company</i>	<i>Last</i>	<i>First</i>	<i>Company</i>	<i>Last</i>	<i>First</i>
<i>SELF</i>	<i>Kawai</i>	<i>Naoyuki</i>	SUMCO	Nakai	Tetsuya
<i>SELF</i>	<i>Yoshise</i>	<i>Masanori</i>	<i>Shin-Etsu Handotai Co., Ltd.</i>	<i>Tsunoda</i>	<i>Hitoshi</i>
<i>Kokusai Electric Corporation</i>	<i>Matsuda</i>	<i>Mitsuhiro</i>	SEMI Japan	Nakajo	Mami
<i>Global Wafers Japan</i>	<i>Takeda</i>	<i>Ryuji</i>	SEMI Japan	Osawa	Naoko
<i>X-FAB Sarawak Sdn. Bhd</i>	<i>Liew</i>	<i>Emily</i>			

Table 2 Leadership Changes

<i>WG/TF/SC/TC Name</i>	<i>Previous Leader</i>	<i>New Leader</i>
None		

Table 3 Committee Structure Changes

<i>Previous WG/TF/SC Name</i>	<i>New WG/TF/SC Name or Status Change</i>
None	

Table 4 Ballot Results

<i>Document #</i>	<i>Document Title</i>	<i>Committee Action</i>
None		

#1 **Passed** ballots and line items will be submitted to the ISC Audit & Review Subcommittee for procedural review.

#2 **Failed** ballots and line items were returned to the originating task forces for re-work and re-balloting or abandoning.

Table 5 Ratification Ballot Results

<i>Document #</i>	<i>Document Title</i>	<i>ISC A&R Action</i>	<i>A&R Forms</i>
None			



Note 1: **Passed** Ratification ballots will be submitted to SEMI publication for final processing.

Note 2: **Failed** Ratification ballots were returned to the originating task forces for re-work and re-balloting or abandoning.

Table 6 Activities Approved by the GCS between meetings of the TC Chapter

#	Type	SC/TF/WG	Details
None			

No activity requested by the Japan TC Chapter between meetings.

Table 7 Authorized Activities

Listing of all revised or new SNARF(s) approved by the Originating TC Chapter.

#	Type	SC/TF/WG	Details
None			

#1 SNARFs and TFOFs are available for review on the SEMI Web site at:

<http://downloads.semi.org/web/wstdsbal.nsf/TFOFSNARE>

Table 8 Authorized Ballots

#	When	TF	Details
None			

Table 9 SNARF(s) Granted a One-Year Extension

#	TF	Title	Expiration Date
None			

Table 10 SNARF(s) Abolished

#	TF	Title
None		

Table 11 Standard(s) to receive Inactive Status

Standard Designation	Title
None	

Table 12 New Action Items

Item #	Assigned to	Details
None		

Table 13 Previous Meeting Action Items

Item #	Assigned to	Details
20230413-01	SEMI Staff	To confirm details with SEMI NA Staff regarding the reapproval documents that the NA co-chair has requested to be transferred to Japan for authorization.> Done



1 Welcome, Reminders, and Introductions

Tetsuya Nakai (SUMCO), called the meeting to order at 10:00. The meeting reminders on antitrust issues, intellectual property issues and holding meetings with international attendance were reviewed. Attendees introduced themselves.

Attachment: 01-02_Required Element Nov 2022_E+J (new template)

2 Review of Previous Meeting Minutes

The TC Chapter reviewed the minutes of the previous meeting.

Motion:	Approve the minutes as written
By / 2nd:	Naoyuki Kawai (Self) / Masanori Yoshise (Self)
Discussion:	None
Vote:	5 in favor and 0 opposed. Motion Passed.

Attachment: 02-01_20221214_Global Silicon Wafer Japan TC Chapter Meeting Minutes_approved_r1

3 Ballot Review

None

4 Subcommittee and Task Force Reports

4.1 International Advanced Wafer Geometry Task Force

Masanori Yoshise (Wafer Information Service) reported for the International Advanced Wafer Geometry Task Force as attached.

Attachment: 04-01_AWG NA SEMICON W 2023 minutes

4.2 International/Japan Test Method Task Force

Ryuji Takeda (Global Wafers Japan) reported for the Japan Test Method Task Force as attached.

Attachment: 04-02_Japan Test Method TF meeting Aug 24 2023

4.3 International Advanced Automated Surface Inspection Task Force

Tetsuya Nakai (SUMCO) reported for the International Advanced Automated Surface Inspection Task Force.

The TF made 2 Working Group.

1. AFM WG: Aim to standardize the measurement of microroughness. Its kick off meeting was held in August 2023.
2. Haze WG: Aim to investigate the correlation of roughness metrics derived from AFM and SSIS data and recommend the optimal configuration.

4.4 International Polished Wafers Task Force

No special topic was reported at this meeting.

4.5 International Epitaxial Wafers Task Force

Tsunoda Hitoshi (Shin-Etsu Handotai) reported that there is no update in the task force.

4.6 International Annealed Wafers Task Force

No special topic was reported at this meeting.

4.7 International SOI Wafers Task Force

Tetsuya Nakai (SUMCO) reported for the SOI Wafers Task Force.

The TF is working on “Specification of 200 mm and 300 mm SOI Wafer for RF Devices” and to be discussed at NA Spring Meeting..

4.8 International Terminology Task Force

No special topic was reported at this meeting.

5 Liaison Reports

5.1 Silicon Wafer Europe TC Chapter

Mami Nakajo (SEMI) reported that there is no update on the Silicon Wafer Europe TC Chapter.

5.2 Silicon Wafer North America TC Chapter

Tetsuya Nakai (SUMCO) reported for the Silicon North America TC Chapter as attached.

Attachment: 05-02_NA Si Wafer TC Chapter Liaison Report July2023

5.3 GCS

No special topic was reported at this meeting.

6 SEMI Staff Report

Mami Nakajo (SEMI) gave the SEMI Staff Report.

Attachment: 06-01_Staff Report July 2023 v3 (1)

7 Old Business

7.1 Project Period Review

None

7.2 5 Year Review Check

7.2.1 SEMI M51-1012: Test Method for Characterizing Silicon Wafer by Gate Oxide Integrity

Ongoing

7.2.2 SEMI M60-1014: Test Method for Time Dependent Dielectric Breakdown Characteristics of SiO₂ Films for Si Wafer Evaluation

Ongoing



8 New Business

8.1 Proposal of New Activity

None

9 Action Item Review

9.1 Open Action Item

<i>Item #</i>	<i>Assigned to</i>	<i>Details</i>
20230413-01	SEMI Staff	To confirm details with SEMI NA Staff regarding the reapproval documents that the NA co-chair has requested to be transferred to Japan for authorization. > Done

9.2 New Action Item

None

10 Next Meeting and Adjournment

The next meeting is scheduled for as follows.

Thursday, December 14, 10:00am-12:00[JST] @ Tokyo Big Sight (via OVTCCM) Hybrid in conjunction with SEMICON Japan 2023.

Please check www.semi.org/standards for updates.

See <http://www.semi.org/standards-events> for the current list of events.

Adjournment: [1130]>.

Respectfully submitted by:

Mami Nakajo

Coordinator

SEMI Japan

Phone: +81.3.3222.5757

Email: mnakajo@semi.org

Minutes tentatively approved by:

Tetsuya Nakai (SUMCO), Co-chair	October 16, 2023
Ryuji Takeda (Global Wafers Japan), Co-chair	October 20, 2023

Table 14 Index of Available Attachments^{#1}

<i>Title</i>	<i>Title</i>
01-02_Required Element Nov 2022_E+J (new template)	05-02_NA Si Wafer TC Chapter Liaison Report July2023



Table 14 Index of Available Attachments^{#1}

02-01_20230413_Global Silicon Wafer Japan TC Chapter Meeting Minutes_approved	06-01_Staff Report July 2023 v3 (1)
04-01_AWG NA SEMICON W 2023 minutes	
04-02_Japan Test Method TF meeting Aug 24 2023	

#1 Due to file size and delivery issues, attachments must be downloaded separately. A .zip file containing all attachments for these minutes is available at www.semi.org. For additional information or to obtain individual attachments, please contact Mami Nakajo at the contact information above.